CLAIM AMENDMENTS

1. Cancelled

2. (Previously Presented) The integrated circuit of claim 4 wherein the interconnection substrate is flip chip bonded to the semiconductor substrate.

3. (Previously Presented) The integrated circuit of claim 4 wherein the interconnection substrate is formed from one of an organic material, ceramic, and silicon.

4. (Currently Amended) An integrated circuit comprising:

   an integrated circuit package having a first plurality of bonding pads;

   a semiconductor substrate within the integrated circuit package, including a circuit and a second plurality of bonding pads, and having a surface area;

   a plurality of wire bonds connecting selected ones of the first plurality of bonding pads to selected ones of the second plurality of bonding pads; and

   an interconnection substrate mounted on the semiconductor substrate, the interconnection substrate having a surface area smaller than the semiconductor substrate surface area~~ and including only a conductive interconnect layer~~.

5. (Previously Presented) The integrated circuit of claim 4 wherein the semiconductor substrate includes peripheral areas about the interconnect substrate and wherein at least some of the second plurality of bonding pads are within the peripheral areas.

6. (Previously Presented) The integrated circuit of claim 4 wherein the interconnection substrate further includes at least one filter capacitor.

7. (Previously Presented) The integrated circuit of claim 4 wherein the integrated circuit package includes a cavity and wherein the semiconductor substrate is adhered to the package within the cavity.

8. (Previously Presented) The integrated circuit of claim 4 wherein the integrated circuit package includes a substrate and wherein the first plurality of bond pads and the semiconductor substrate are carried by the integrated circuit package substrate.

9. Cancelled

10. (Previously Presented) The integrated circuit of claim 11 wherein the interconnection substrate is formed from one of an organic material, ceramic, and silicon.

11. (Currently Amended) An integrated circuit comprising:

an integrated circuit package having a first plurality of bonding pads;

a semiconductor substrate within the integrated circuit package, including a circuit and a second plurality of bonding pads, and having a surface area;

a plurality of wire bonds connecting selected ones of the first plurality of bonding pads to selected ones of the second plurality of bonding pads; and

an interconnection substrate flip chip mounted on the semiconductor substrate, the interconnection substrate ~~including only a conductive interconnect layer and~~ having a surface area smaller than the semiconductor substrate surface area forming exposed peripheral areas in the semiconductor substrate and wherein

the second plurality of bonding pads are within the peripheral areas.

12. (Previously Presented) The integrated circuit of claim 11 wherein the interconnection substrate further includes at least one filter capacitor.

13. (Previously Presented) The integrated circuit of claim 11 wherein the integrated circuit package includes a cavity and wherein the semiconductor substrate is adhered to the package within the cavity.

14. (Previously Presented) The integrated circuit of claim 11 wherein the integrated circuit package includes a substrate and wherein the first plurality of bond pads and the semiconductor substrate are carried by the integrated circuit package substrate.

15. Cancelled

16. (Previously Presented) The integrated circuit assembly of claim 17 wherein the interconnection substrate is formed from one of an organic material, ceramic, and silicon.

17. (Currently Amended) An integrated circuit assembly comprising:

a semiconductor substrate including a circuit and a plurality of bonding pads, and having a surface area; and

an interconnection substrate flip chip mounted on the semiconductor substrate, the interconnection substrate having a surface area smaller than the semiconductor substrate surface area~~ and including only a conductive interconnect layer~~.

18. (Previously Presented) The integrated circuit assembly of claim 17 wherein the semiconductor substrate includes peripheral areas about the interconnect substrate and wherein at least some of the plurality of bonding pads are within the peripheral areas.

19. (Previously Presented) The integrated circuit assembly of claim 17 further including at least one filter capacitor carried by the interconnection substrate.

20. (Previously Presented) An integrated circuit assembly comprising:

a semiconductor substrate including a circuit and a plurality of bonding pads, and having a surface area; and

an interconnection substrate flip chip mounted on the semiconductor substrate and operable to receive power directly from a third substrate and distribute the power to the semiconductor substrate, the interconnection substrate having a surface area smaller than the semiconductor substrate surface area.

21. (Previously Presented) The circuit assembly of claim 20 wherein a wire bond connects the interconnection substrate to the third substrate.

22. (Previously Presented) The circuit assembly of claim 20 wherein the interconnection substrate further includes at least one filter capacitor.